



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20231213001.1
Qualification of additional Assembly sites for select HSOIC devices
Change Notification / Sample Request

Date: December 21, 2023

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20231213001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BUF634AIDDAR	null
DRV8871DDAR	null
LM5012DDAR	null
LM5013DDAR	null
LMR38010FDDAR	null
LMR38010SDDAR	null
LMR38020FDDAR	null
LMR38020FSDDAR	null
LMR38020SDDAR	null
THS3491IDDAR	null
THS3491IDDAT	null
TPS259620DDAR	null
TPS259620DDAT	null
TPS259621DDAR	null
TPS259621DDAT	null
TPS259630DDAR	null
TPS259630DDAT	null
TPS259631DDAR	null
TPS259631DDAT	null
TPS54229DDA	null
TPS54229DDAR	null
TPS54229EDDAR	null
TPS54239DDA	null
TPS54239DDAR	null
TPS54239EDDA	null
TPS54239EDDAR	null
TPS5432DDA	null
TPS5432DDAR	null
TPS54334DDA	null
TPS54334DDAR	null
TPS54339DDA	null
TPS54339DDAR	null
TPS54339EDDAR	null
TPS566250DDA	null
TPS7A7001DDA	null
TPS7A7001DDAR	null
TPS7A7002DDA	null
TPS7A7002DDAR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20231213001.1		PCN Date:	December 21, 2023	
Title:	Qualification of additional Assembly sites for select HSOIC devices				
Customer Contact:	Change Management Team	Dept:	Quality Services		
Proposed 1st Ship Date:	Mar 20, 2024	Sample requests accepted until:	Jan 21, 2024*		
*Sample requests received after Jan 21, 2024 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:					
HSOIC Build sites					
Assembly Sites	FMX, ASESAT, AP1, HNA, TITL				
Mold Compound	4211880, SID#EN2000509, SID#EN20000519, SID#101379294, SID#450207, SID#450042, 4211649, 4205443				
Mount Compound	4223772, 4147858, 4224264, SID#EY2000030, SID#EY1000063, SID#EY1000102, SID#101375281, SID#400728, 4042504, 4208458				
LeadFrame Finish	NiPdAu, Matte Sn				
Bond Wire	Cu, Au				
<p>Upon expiration of this PCN, TI will combine lead free solutions in a single <u>standard part number</u>, for example; <u>DRV8871DDAR</u> – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. <u>DRV8871DDAR.</u>”</p>					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					

None

Impact on Environmental Ratings


Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

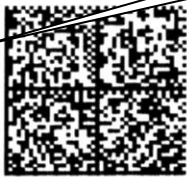
RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Assembly Sites		
HNA	Assembly Site Origin (22L)	ASO: HNT
AP1	Assembly Site Origin (22L)	ASO: AKR
ASESH	Assembly Site Origin (22L)	ASO: ASH
FMX	Assembly Site Origin (22L)	ASO: MEX
TITL	Assembly Site Origin (22L)	ASO: TAI

Sample product shipping label (not actual product label)

**TEXAS
INSTRUMENTS**
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750


G4

E4/G4: NiPdAu
E3/G3: Matte Sn

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

BUF634AIDDAR	SN1106042DDAR	TPS259631DDAR	TPS54332CDDAR
DRV8871DDAR	SN1110024DDAR	TPS259631DDAT	TPS54334DDA
LM5012DDAR	SN1208017DDAR	TPS54229DDA	TPS54334DDAR
LM5013DDAR	SN1208022DDAR	TPS54229DDAR	TPS54339DDA
LMR38010FDDAR	SN54229EDDAR	TPS54229EDDA	TPS54339DDAR
LMR38010FSDDAR	THS3491IDDAR	TPS54229EDDAR	TPS54339EDDA
LMR38010SDDAR	THS3491IDDAT	TPS54239DDA	TPS54339EDDAR
LMR38020FDDAR	TPS259620DDAR	TPS54239DDAR	TPS566250DDA
LMR38020FSDDAR	TPS259620DDAT	TPS54239EDDA	TPS566250DDAR
LMR38020SDDAR	TPS259621DDAR	TPS54239EDDAR	TPS7A7001DDA
SN1101002DDAR	TPS259621DDAT	TPS54328RDDAR	TPS7A7001DDAR
SN1106039DDAR	TPS259630DDAR	TPS5432DDA	TPS7A7002DDA
SN1106041DDAR	TPS259630DDAT	TPS5432DDAR	TPS7A7002DDAR



**TI Information
Selective Disclosure**

HSOIC Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	FMX DRV8251DDA LM5163DDA	ASESH LMR38020SDDA OPA462IDDA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAS T/TH B	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHA ST/A C	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	HNA OPA454AIDDA OPA2211AIDDA	TITL TPA1517DWP OPA564AQDWPRQ 1
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAS T/TH B	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHA ST/A C	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	AP1 TPS54327DDA THS6052IDDA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0
HAST /THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0
UHA	Unbiased HAST, 130C/85%RH	96 hours	3/231/0

	Stress Test	Duration	AP1 TPS54327DDA THS6052IDDA
ST/A C	Or Autoclave 121C		
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0
MQ	Manufacturability	-	Pass

Device THS6052IDDA qualified at L1-260C MSL rating

Devices TPS54327DDA, LMR38020SDDA, LM5163DDA, OPA454AIDDA, OPA2211AIDDA, TPA1517DWP, OPA462IDDA qualified at L2-260C MSL rating

Devices DRV8251DDA, OPA564AQDWPRQ1, qualified at L3-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HT SL, as applicable
- The following are equivalent HT SL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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